1. General description

PNP medium power transistors in an ultra thin SOT1061 leadless small Surface-Mounted Device (SMD) plastic package.

2. Features and benefits

- High current
- Three current gain selections
- High power dissipation capability
- Exposed heatsink for excellent thermal and electrical conductivity
- Leadless very small SMD plastic package with medium power capability
- AEC-Q101 qualified

3. Applications

- Linear voltage regulators
- High-side switches
- Battery-driven devices
- Power management
- MOSFET drivers
- Amplifiers

4. Quick reference data

Table 1. Quick reference data

\( T_{\text{amb}} = 25 \, ^\circ\text{C} \) unless otherwise specified.

<table>
<thead>
<tr>
<th>Symbol</th>
<th>Parameter</th>
<th>Conditions</th>
<th>Conditions</th>
<th>Min</th>
<th>Typ</th>
<th>Max</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>( V_{\text{CEO}} )</td>
<td>collector-emitter voltage</td>
<td>open base</td>
<td></td>
<td>-</td>
<td>-</td>
<td>-80</td>
<td>V</td>
</tr>
<tr>
<td>( I_{\text{C}} )</td>
<td>collector current</td>
<td></td>
<td></td>
<td>-</td>
<td>-</td>
<td>-1</td>
<td>A</td>
</tr>
<tr>
<td>( I_{\text{CM}} )</td>
<td>peak collector current</td>
<td>single pulse; ( t_p \leq 1 , \text{ms} )</td>
<td></td>
<td>-</td>
<td>-</td>
<td>-2</td>
<td>A</td>
</tr>
<tr>
<td>( h_{\text{FE}} )</td>
<td>DC current gain</td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>BC53PA</td>
<td></td>
<td></td>
<td></td>
<td>[1] 63</td>
<td>-</td>
<td>250</td>
<td></td>
</tr>
<tr>
<td>BC53-10PA</td>
<td></td>
<td>( V_{\text{CE}} = -2 , \text{V}; I_{\text{C}} = -150 , \text{mA} )</td>
<td></td>
<td>[1] 63</td>
<td>-</td>
<td>160</td>
<td></td>
</tr>
<tr>
<td>BC53-16PA</td>
<td></td>
<td>( T_{\text{amb}} = 25 , ^\circ\text{C} )</td>
<td></td>
<td>[1] 100</td>
<td>-</td>
<td>250</td>
<td></td>
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[1] pulsed; \( t_p \leq 300 \, \mu\text{s} \); \( \delta \leq 0.02 \)
5. Pinning information

Table 2. Pinning

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<thead>
<tr>
<th>Pin</th>
<th>Symbol</th>
<th>Description</th>
<th>Simplified outline</th>
<th>Graphic symbol</th>
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<td>1</td>
<td>B</td>
<td>base</td>
<td>Transparent top view</td>
<td></td>
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<tr>
<td>2</td>
<td>E</td>
<td>emitter</td>
<td></td>
<td></td>
</tr>
<tr>
<td>3</td>
<td>C</td>
<td>collector</td>
<td></td>
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6. Ordering information

Table 3. Ordering information

<table>
<thead>
<tr>
<th>Type number</th>
<th>Package</th>
<th>Name</th>
<th>Description</th>
<th>Version</th>
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<tr>
<td>BC53PA</td>
<td>-</td>
<td>plastic, leadless thermal enhanced ultra thin small outline package; no leads; 3 terminals; 2 mm x 2 mm x 0.65 mm body</td>
<td>SOT1061</td>
<td></td>
</tr>
<tr>
<td>BC53-10PA</td>
<td>-</td>
<td>plastic, leadless thermal enhanced ultra thin small outline package; no leads; 3 terminals; 2 mm x 2 mm x 0.65 mm body</td>
<td>SOT1061</td>
<td></td>
</tr>
<tr>
<td>BC53-16PA</td>
<td>-</td>
<td>plastic, leadless thermal enhanced ultra thin small outline package; no leads; 3 terminals; 2 mm x 2 mm x 0.65 mm body</td>
<td>SOT1061</td>
<td></td>
</tr>
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7. Marking

Table 4. Marking

<table>
<thead>
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<th>Type number</th>
<th>Marking code</th>
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<tr>
<td>BC53PA</td>
<td>BV</td>
</tr>
<tr>
<td>BC53-10PA</td>
<td>BW</td>
</tr>
<tr>
<td>BC53-16PA</td>
<td>BX</td>
</tr>
</tbody>
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8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

$T_{\text{amb}} = 25 \degree \text{C}$ unless otherwise specified.

<table>
<thead>
<tr>
<th>Symbol</th>
<th>Parameter</th>
<th>Conditions</th>
<th>Min</th>
<th>Max</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>$V_{\text{CBO}}$</td>
<td>collector-base voltage</td>
<td>open emitter</td>
<td>-</td>
<td>-100 V</td>
<td></td>
</tr>
<tr>
<td>$V_{\text{CEO}}$</td>
<td>collector-emitter voltage</td>
<td>open base</td>
<td>-</td>
<td>-80 V</td>
<td></td>
</tr>
<tr>
<td>$V_{\text{EBO}}$</td>
<td>emitter-base voltage</td>
<td>open collector</td>
<td>-</td>
<td>-5 V</td>
<td></td>
</tr>
<tr>
<td>$I_C$</td>
<td>collector current</td>
<td></td>
<td>-</td>
<td>-1 A</td>
<td></td>
</tr>
<tr>
<td>$I_{\text{CM}}$</td>
<td>peak collector current</td>
<td>single pulse; $t_p \leq 1 \text{ ms}$</td>
<td>-</td>
<td>-2 A</td>
<td></td>
</tr>
<tr>
<td>$I_B$</td>
<td>base current</td>
<td></td>
<td>-</td>
<td>-0.3 A</td>
<td></td>
</tr>
<tr>
<td>$I_{\text{BM}}$</td>
<td>peak base current</td>
<td>single pulse; $t_p \leq 1 \text{ ms}$</td>
<td>-</td>
<td>-0.3 A</td>
<td></td>
</tr>
<tr>
<td>$P_{\text{tot}}$</td>
<td>total power dissipation</td>
<td>$T_{\text{amb}} \leq 25 \degree \text{C}$</td>
<td>[1]</td>
<td>0.42 W</td>
<td></td>
</tr>
<tr>
<td></td>
<td></td>
<td></td>
<td>[2]</td>
<td>0.83 W</td>
<td></td>
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<td></td>
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<td>[3]</td>
<td>1.10 W</td>
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<td></td>
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<td></td>
<td>[4]</td>
<td>0.81 W</td>
<td></td>
</tr>
<tr>
<td></td>
<td></td>
<td></td>
<td>[5]</td>
<td>1.65 W</td>
<td></td>
</tr>
<tr>
<td>$T_j$</td>
<td>junction temperature</td>
<td></td>
<td>-</td>
<td>150 °C</td>
<td></td>
</tr>
<tr>
<td>$T_{\text{amb}}$</td>
<td>ambient temperature</td>
<td></td>
<td>-55</td>
<td>150 °C</td>
<td></td>
</tr>
<tr>
<td>$T_{\text{stg}}$</td>
<td>storage temperature</td>
<td></td>
<td>-65</td>
<td>150 °C</td>
<td></td>
</tr>
</tbody>
</table>

[1] Device mounted on an FR4 Printed-Circuit-Board (PCB); single-sided copper; tin-plated and standard footprint.
[2] Device mounted on an FR4 PCB; single-sided copper; tin-plated; mounting pad for collector 1 cm$^2$.
[3] Device mounted on an FR4 PCB; single-sided copper; tin-plated; mounting pad for collector 6 cm$^2$.
[5] Device mounted on an FR4 PCB, 4-layer copper, tin-plated, mounting pad for collector 1 cm$^2$.

![Power derating curves SOT1061](image)

(1) FR4 PCB, 4-layer copper, mounting pad for collector 1 cm$^2$
(2) FR4 PCB, single-sided copper, mounting pad for collector 6 cm$^2$
(3) FR4 PCB, single-sided copper, mounting pad for collector 1 cm$^2$
(4) FR4 PCB, 4-layer copper, standard footprint
(5) FR4 PCB, single-sided copper, standard footprint

Fig. 1. Power derating curves SOT1061
9. Thermal characteristics

Table 6. Thermal characteristics

\( T_{\text{amb}} = 25 \, ^{\circ}\text{C} \) unless otherwise specified.

<table>
<thead>
<tr>
<th>Symbol</th>
<th>Parameter</th>
<th>Conditions</th>
<th>Min</th>
<th>Typ</th>
<th>Max</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>( R_{(j-a)} )</td>
<td>thermal resistance from junction to ambient</td>
<td>in free air</td>
<td>[1]</td>
<td>-</td>
<td>-</td>
<td>298  K/W</td>
</tr>
<tr>
<td></td>
<td></td>
<td></td>
<td>[2]</td>
<td>-</td>
<td>-</td>
<td>151  K/W</td>
</tr>
<tr>
<td></td>
<td></td>
<td></td>
<td>[3]</td>
<td>-</td>
<td>-</td>
<td>114  K/W</td>
</tr>
<tr>
<td></td>
<td></td>
<td></td>
<td>[5]</td>
<td>-</td>
<td>-</td>
<td>76   K/W</td>
</tr>
</tbody>
</table>

[2] Device mounted on an FR4 PCB; single-sided copper; tin-plated; mounting pad for collector 1 cm\(^2\).
[3] Device mounted on an FR4 PCB; single-sided copper; tin-plated; mounting pad for collector 6 cm\(^2\).
[5] Device mounted on an FR4 PCB, 4-layer copper, tin-plated, mounting pad for collector 1 cm\(^2\).

---

**FR4 PCB; single-sided copper; tin-plated and standard footprint**

**Fig. 2.** Transient thermal impedance from junction to ambient as a function of pulse duration; typical values
80 V, 1 A PNP medium power transistors

Fig. 3. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

FR4 PCB; single-sided copper; tin-plated; mounting pad for collector 1 cm²

Fig. 4. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

FR4 PCB; single-sided copper; tin-plated; mounting pad for collector 6 cm²

Fig. 5. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

FR4 PCB; 4-layer copper, standard footprint

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Fig. 6. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

FR4 PCB; 4-layer copper; mounting pad for collector 1 cm²
### 10. Characteristics

#### Table 7. Characteristics

<table>
<thead>
<tr>
<th>Symbol</th>
<th>Parameter</th>
<th>Conditions</th>
<th>Min</th>
<th>Typ</th>
<th>Max</th>
<th>Unit</th>
</tr>
</thead>
</table>
| $I_{CBO}$ | collector-base cut-off current | $V_{CB} = -30 V; I_{E} = 0 A$  
$T_{amb} = 25 \, ^\circ C$ |      |      | -100 | nA   |
|        |                               | $V_{CB} = -30 V; I_{E} = 0 A; T_{j} = 150 \, ^\circ C$ |      |      | -10  | µA   |
| $I_{EBO}$ | emitter-base cut-off current | $V_{EB} = -5 V; I_{C} = 0 A$  
$T_{amb} = 25 \, ^\circ C$ |      |      | -100 | nA   |
| $h_{FE}$ | DC current gain               | $V_{CE} = -2 V; I_{C} = -5 mA$  
$T_{amb} = 25 \, ^\circ C$ | 63  | -    | -    |      |
|        |                               | $V_{CE} = -2 V; I_{C} = -150 mA$  
$T_{amb} = 25 \, ^\circ C$ | 63  | -    | 250  |      |
|        |                               | $V_{CE} = -2 V; I_{C} = -500 mA$  
$T_{amb} = 25 \, ^\circ C$ | 40  | -    | -    |      |
|        | $BC53-10PA$                   | $V_{CE} = -2 V; I_{C} = -5 mA$  
$T_{amb} = 25 \, ^\circ C$ | 63  | -    | -    |      |
|        |                               | $V_{CE} = -2 V; I_{C} = -150 mA$  
$T_{amb} = 25 \, ^\circ C$ | 63  | -    | 160  |      |
|        |                               | $V_{CE} = -2 V; I_{C} = -500 mA$  
$T_{amb} = 25 \, ^\circ C$ | 40  | -    | -    |      |
|        | $BC53-16PA$                   | $V_{CE} = -2 V; I_{C} = -5 mA$  
$T_{amb} = 25 \, ^\circ C$ | 63  | -    | -    |      |
|        |                               | $V_{CE} = -2 V; I_{C} = -150 mA$  
$T_{amb} = 25 \, ^\circ C$ | 100 | -    | 250  |      |
|        |                               | $V_{CE} = -2 V; I_{C} = -500 mA$  
$T_{amb} = 25 \, ^\circ C$ | 40  | -    | -    |      |
| $V_{CE\text{sat}}$ | collector-emitter saturation voltage | $I_{C} = -500 mA; I_{E} = -50 mA$  
$T_{amb} = 25 \, ^\circ C$ |      |      | -0.5 | V    |
| $V_{BE}$ | base-emitter voltage          | $V_{CE} = -2 V; I_{C} = -500 mA$  
$T_{amb} = 25 \, ^\circ C$ |      |      | -1   | V    |
| $C_{C}$ | collector capacitance         | $V_{CB} = -10 V; I_{E} = i_{e} = 0 A; f = 1 \, MHz$  
$T_{amb} = 25 \, ^\circ C$ |      | 15   | -    | pF   |
| $f_{T}$ | transition frequency          | $V_{CE} = -5 V; I_{C} = -50 mA; f = 100 \, MHz$  
$T_{amb} = 25 \, ^\circ C$ |      | 145  | -    | MHz  |

[1] pulsed; $t_{p} \leq 300 \, \mu s; \delta \leq 0.02$
**BC53PA series**

80 V, 1 A PNP medium power transistors

---

**Fig. 7.** DC current gain as a function of collector current; typical values

- $V_{CE} = -2 \, \text{V}$
- (1) $T_{\text{amb}} = 100 \, ^\circ\text{C}$
- (2) $T_{\text{amb}} = 25 \, ^\circ\text{C}$
- (3) $T_{\text{amb}} = -55 \, ^\circ\text{C}$

**Fig. 8.** Collector current as a function of collector-emitter voltage; typical values

- $T_{\text{amb}} = 25 \, ^\circ\text{C}$

**Fig. 9.** Base-emitter voltage as a function of collector current; typical values

- $V_{CE} = -2 \, \text{V}$
- (1) $T_{\text{amb}} = -55 \, ^\circ\text{C}$
- (2) $T_{\text{amb}} = 25 \, ^\circ\text{C}$
- (3) $T_{\text{amb}} = 100 \, ^\circ\text{C}$

**Fig. 10.** Collector-emitter saturation voltage as a function of collector current; typical values

- $I_{C}/I_{B} = 10$
- (1) $T_{\text{amb}} = 100 \, ^\circ\text{C}$
- (2) $T_{\text{amb}} = 25 \, ^\circ\text{C}$
- (3) $T_{\text{amb}} = -55 \, ^\circ\text{C}$
11. Test information

11.1. Quality information
This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - Stress test qualification for discrete semiconductors, and is suitable for use in automotive applications.

12. Package outline

Fig. 11. Package outline SOT1061
13. Soldering

Fig. 12. Reflow soldering footprint for SOT1061
# 14. Revision history

<table>
<thead>
<tr>
<th>Document ID</th>
<th>Release date</th>
<th>Data sheet status</th>
<th>Change notice</th>
<th>Supersedes</th>
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<td>20230804</td>
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<td>BCP53_BCX53_BC53PA v.9</td>
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15. Legal information

Data sheet status

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<tr>
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<th>Product status</th>
<th>Definition</th>
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<td>Development</td>
<td>This document contains data from the objective specification for product development.</td>
</tr>
<tr>
<td>Preliminary [short] data sheet</td>
<td>Qualification</td>
<td>This document contains data from the preliminary specification.</td>
</tr>
<tr>
<td>Product [short] data sheet</td>
<td>Production</td>
<td>This document contains the product specification.</td>
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</table>

[1] Please consult the most recently issued document before initiating or completing a design.
[2] The term "short data sheet" is explained in section "Definitions".
[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the internet at https://www.nexperia.com.

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